

# MA2J1130G

## Silicon epitaxial planar type

For switching circuits

### ■ Features

- Allowing high-density mounting
- Ensuring the forward current (Average) capacity  $I_{F(AV)} = 200$  mA
- High breakdown voltage:  $V_R = 80$  V

### ■ Package

- Code  
SMini2-F3
- Pin Name  
1: Anode  
2: Cathode

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current (Average)	$I_{F(AV)}$	200	mA
Peak forward current	$I_{FM}$	600	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Marking Symbol: 1D

Note) \*:  $t = 1$  s

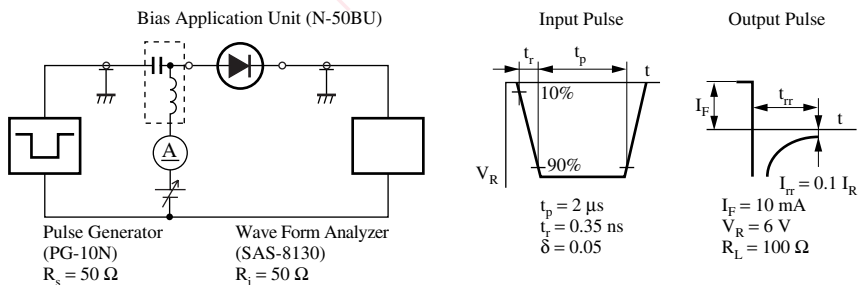
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

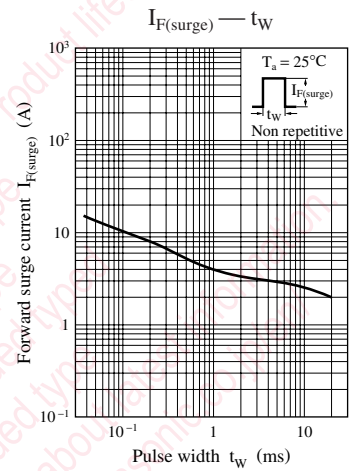
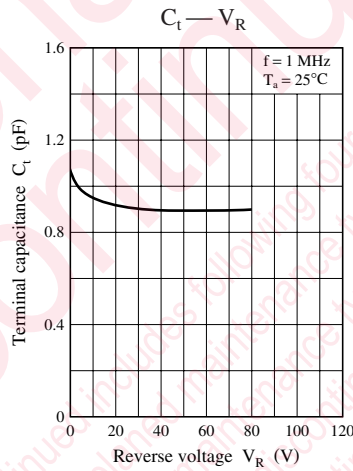
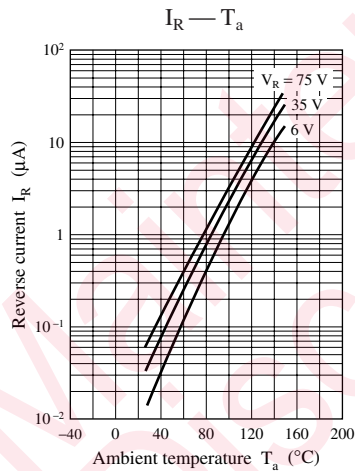
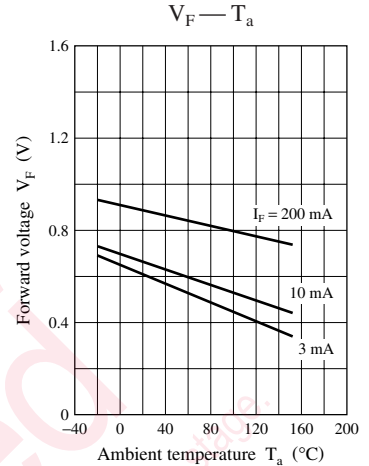
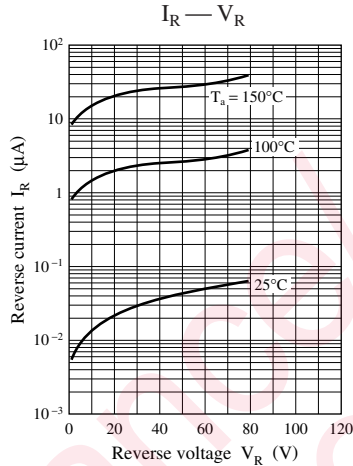
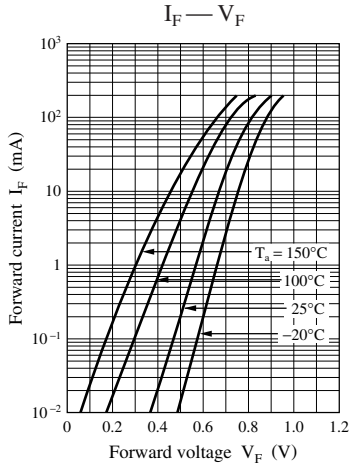
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200$ mA			1.1	V
Reverse current	$I_{R1}$	$V_R = 15$ V			50	nA
	$I_{R2}$	$V_R = 75$ V			500	nA
	$I_{R3}$	$V_R = 75$ V, $T_a = 100^\circ\text{C}$			100	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz			4	pF
Reverse recovery time *	$t_{rr}$	$I_F = 10$ mA, $V_R = 6$ V $I_{tr} = 0.1 I_R$ , $R_L = 100 \Omega$			10	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

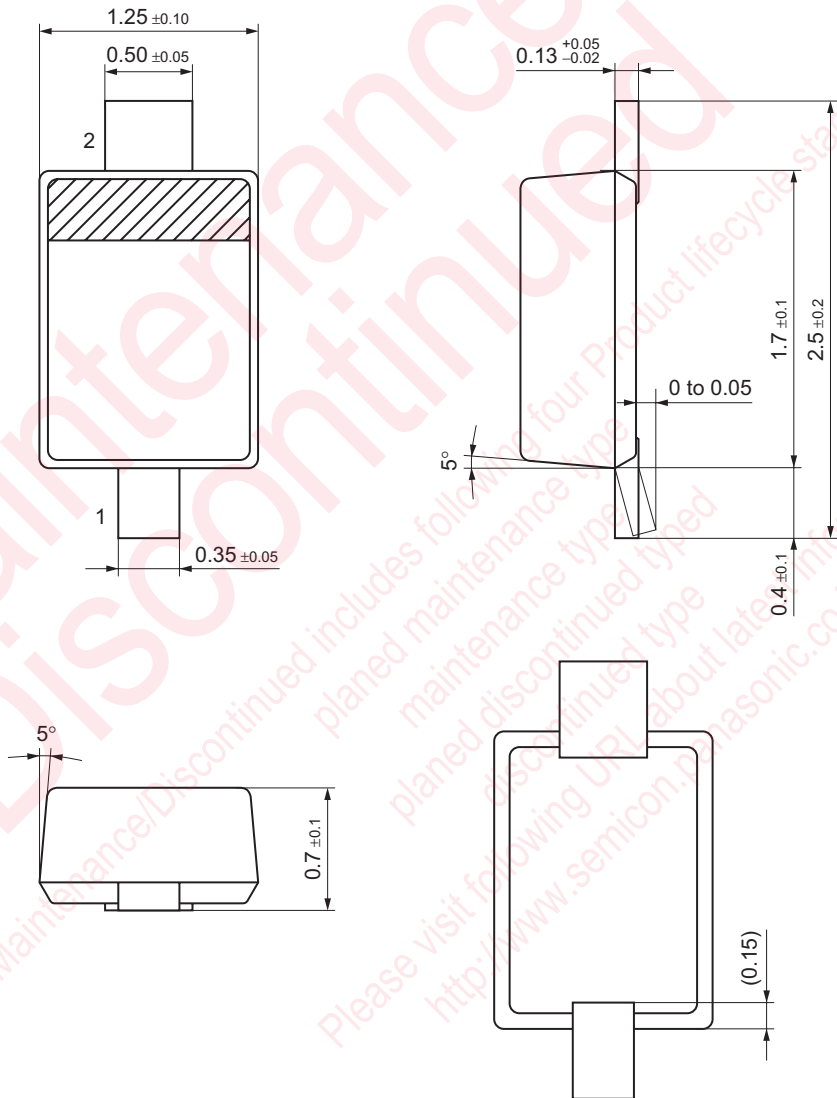
3. \*:  $t_{rr}$  measurement circuit





SMini2-F3

Unit: mm



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